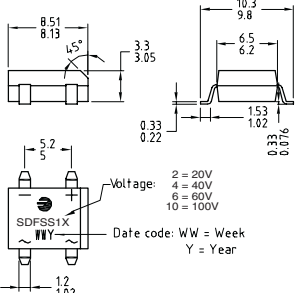
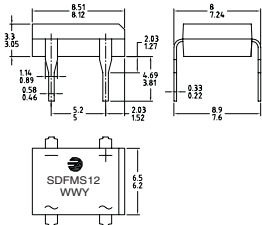


1.0 Amp. Schottky Barrier Rectifiers

<p>Dimensions in mm.</p> <p>DF - S</p>  <p>DF - M</p> 	<p>Voltage 20 to 100 V.</p> <p>Current 1.0 Amp.</p>	<ul style="list-style-type: none"> • Glass Passivated Junction • Package: DF-S for surface mount package and DF-M for Dual in Line. • Ideal for PCB • Lead and polarity identifications • Metal to silicon rectifier, majority carrier • Low forward voltage drop • High surge current capability • Laboratory Classification 94V-0 • High temperature soldering: 260°C / 10 seconds at terminals • Small size, single installation lead solderable per MIL-STD-202 Method 208
--	---	--

Maximum Ratings, according to IEC publication No. 134

		SDFMS12	SDFMS14	SDFMS16	SDFMS110
		SDFSS12	SDFSS14	SDFSS16	SDFSS110
V_{RRM}	Peak Recurrent Reverse Voltage (V)	20	40	60	100
V_{RMS}	Maximum RMS Voltage (V)	14	28	42	70
V_{DC}	Maximum DC Blocking Voltage	20	40	60	100
$I_{(AV)}$	Maximum Average Forward Rectifier current at T_L	1.0 A			
I_{FSM}	8.3 ms. peak forward current (Jedec Method)	30 A			
T_j	Operating temperature range	- 65 to + 125 °C		- 65 to + 150 °C	
T_{STG}	Storage temperature range	- 65 to + 150 °C			

Electrical Characteristics at $T_{amb} = 25\text{ °C}$

V_F	Max. forward voltage drop at $I_F = 1.0\text{ A}$ (Note 1)	0.5 V	0.75 V	0.80 V
I_R	Max. reverse DC current and $T = 25\text{ °C}$ at Rated DC Blocking Voltage and $T = 100\text{ °C}$	0.4 mA		0.05 mA
		10 mA	5 mA	0.5 mA
$R_{th(j-a)}$	Maximum thermal resistance junction to ambient (Note 2)	28 °C/W		
$R_{th(j-l)}$	Maximum thermal resistance junction to lead	88 °C/W		
C_j	Typical Junction Capacitance (Note 3)	50 pF		

NOTES: 1. Pulse Test With $PW = 300\text{ }\mu\text{sec}$, 1% Duty Cycle
2. Measured on P.C. Board with 12mm x 12mm Copper Pad Areas.
3. Measured at 1 MHz and Applied Reverse Voltage of 4.0 D.C.

Characteristic Curves

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

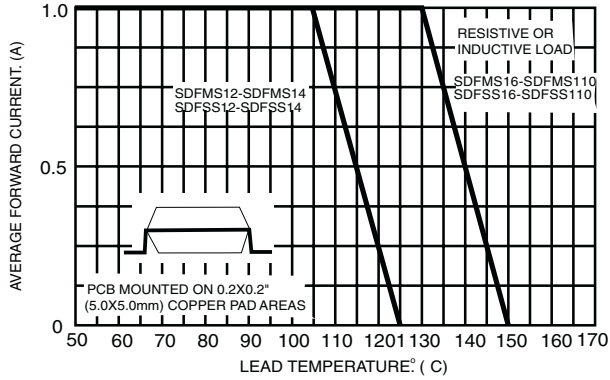


FIG.2- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

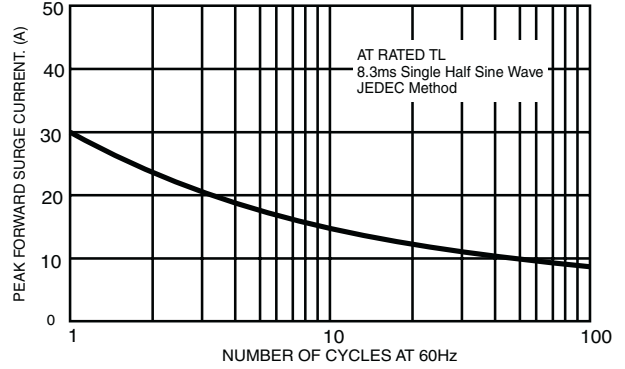


FIG.3- TYPICAL FORWARD CHARACTERISTICS

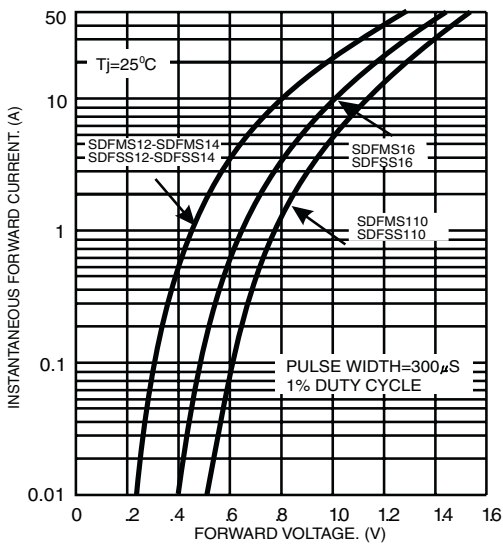


FIG.4- TYPICAL REVERSE CHARACTERISTICS

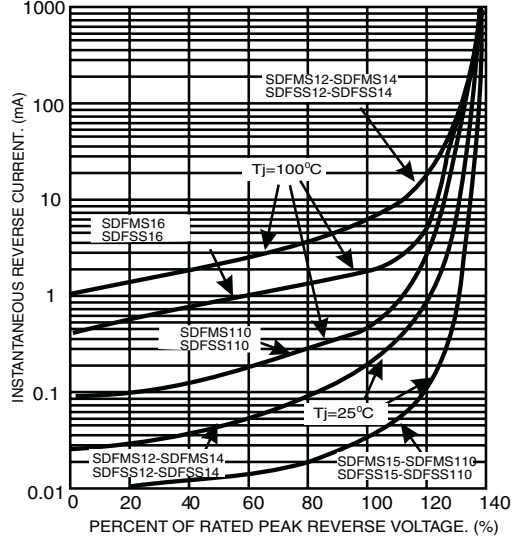


FIG.5- TYPICAL JUNCTION CAPACITANCE

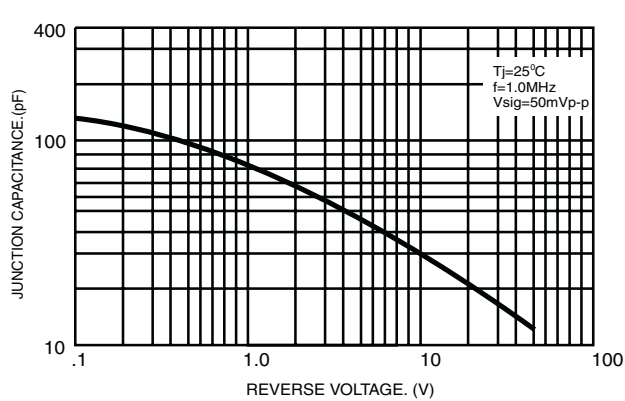


FIG.6- TYPICAL TRANSIENT THERMAL CHARACTERISTICS

